









# CEP07N7

#### 700V **Δ** 1.3Ω **Δ** 6.6A **Δ** Si MOSFET

SILICON Si MOSFET ▲ THT type
N-channel enhancement mode
UL94V-0 rated flame retardant epoxy
TO220-3L package

Super high dense cell density for extremely low R<sub>DS(ON)</sub> **High power and current handling capability** 

## **MAXIMUM RATINGS**

Parameter (T <sub>c</sub> = 25°C, unless otherwise noted)		Characteristics
Drain-Source Voltage	V <sub>DS</sub>	700V
Gate-Source Voltage	V <sub>GS</sub>	±30V
Continuous Drain Current at T <sub>C</sub> = 25°C	I <sub>D</sub>	6A
Pulsed Drain Current Note 1	I <sub>DM</sub> Note 4	26.4A
Maximum Power Dissipation at T <sub>C</sub> = 25°C	P <sub>D</sub>	166W
Power Dissipation Derating above 25°C	ΔP <sub>D</sub>	1.3W/°C
Repetitive Avalanche Energy	E <sub>AR</sub>	3.6mJ
Single Pulsed Avalanche Energy Note 5	E <sub>AS</sub>	38.88mJ
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55°C to +150°C

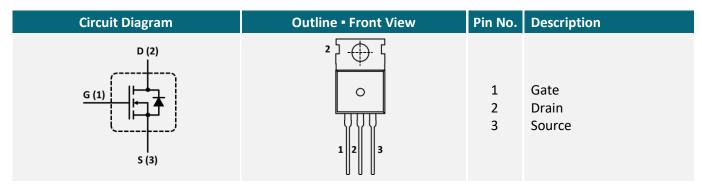
## THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case	R <sub>TH_JC</sub>	0.75°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>TH_JA</sub>	62.5°C/W

#### **APPLICATIONS**

EV Charging	Industrial Inverters	Motors & Drives	Power Factor Correction	Renewable Energy	SMPS	UPS
<b>₹</b> /•			PFC	*		

## **PIN DESCRIPTION**





# **ELECTRICAL CHARACTERISTICS** ▲ T<sub>C</sub> = 25°C, unless otherwise noted

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V$ , $I_{D} = 250 \mu A$	$BV_{DSS}$	700			V
Zero Gate Voltage Drain Current	$V_{DS} = 700V, V_{GS} = 0V$	I <sub>DSS</sub>			1	μΑ
Gate Body Leakage Current, Forward	$V_{GS}$ = 30V, $V_{DS}$ = 0V	$I_{GSSF}$			100	nA
Gate Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	$I_{GSSR}$			-100	nA
On Characteristics Note 2						
Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250 \mu A$	$V_{GS(th)}$	2		4	V
Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 4.5A$	R <sub>DS(ON)</sub>		1.3	1.5	Ω
Dynamic Characteristics Note 3						
Input Capacitance	$V_{DS} = 25V$ , $V_{GS} = 0V$ , $f = 1MHz$	C <sub>ISS</sub>		1215		pF
Output Capacitance	$V_{DS} = 25V$ , $V_{GS} = 0V$ , $f = 1MHz$	Coss		125		pF
Reverse Transfer Capacitance	$V_{DS} = 25V$ , $V_{GS} = 0V$ , $f = 1MHz$	$C_{RSS}$		15		pF
Switching Characteristics Note 3						
Turn-On Delay Time	$V_{DD} = 300V$ , $V_{GS} = 10V$ , $I_{D} = 16.6A$ , $R_{G(ext)} = 25\Omega$	$t_{\text{D(ON)}}$		27		ns
Turn-On Rise Time	$V_{DD} = 300V$ , $V_{GS} = 10V$ , $I_{D} = 16.6A$ , $R_{G(ext)} = 25\Omega$	$t_R$		22		ns
Turn-Off Delay Time	$V_{DD}$ = 300V, $V_{GS}$ = 10V, $I_{D}$ = 16.6A, $R_{G(ext)}$ = 25 $\Omega$	$t_{D(OFF)}$		68		ns
Turn-Off Fall Time	$V_{DD} = 300V$ , $V_{GS} = 10V$ , $I_{D} = 16.6A$ , $R_{G(ext)} = 25\Omega$	t <sub>F</sub>		18		ns
Total Gate Charge	$V_{DS}$ = 480V, $V_{GS}$ = 10V, $I_D$ = 6.6A	$Q_{G}$		23		nC
Gate Source Charge	$V_{DS}$ = 480V, $V_{GS}$ = 10V, $I_{D}$ = 6.6A	$Q_{GS}$		7		nC
Gate Drain Charge	$V_{DS}$ = 480V, $V_{GS}$ = 10V, $I_{D}$ = 6.6A	$Q_{GD}$		6		nC
<b>Drain-Source Diode Characteristics an</b>	nd Maximum Ratings					
Drain-Source Diode Forward Current		Is			6.6	Α
Drain-Source Diode Forward Voltage Note 2	$V_{GS} = 0V$ , $I_S = 5A$	$V_{SD}$			1.4	V

#### **Notes**

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 3: Guaranteed by design, not subject to production testing.
- 4: Pulse width limited by safe operating area.
- 5: L = 6mH,  $I_{AS}$  = 3.6A,  $V_{DD}$  = 50V,  $R_{G}$  = 25Ω, Starting  $T_{J}$  = 25°C.



#### REFERENCE DATA A TYPICAL DEVICE PERFORMANCE



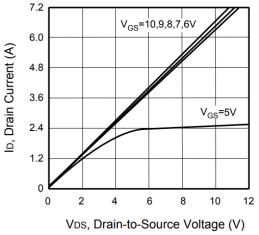


Fig. 2 • Transfer Characteristics

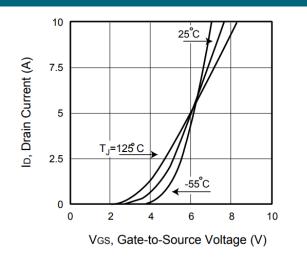


Fig. 3 • Capacitance

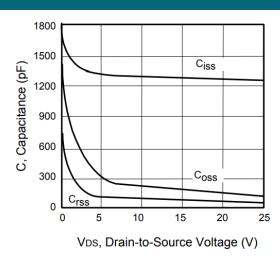


Fig. 4 • On-Resistance Variation with Temperature

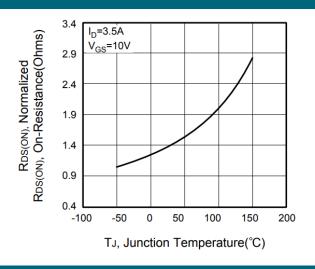


Fig. 5 • Gate Threshold Variation with Temperature

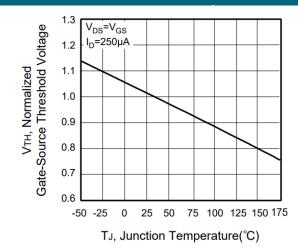
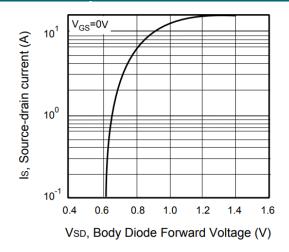


Fig. 6 • Body Diode Forward Voltage Variation with Source Current



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#### REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

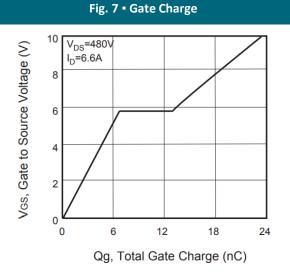


Fig. 8 • Maximum Safe Operating Area

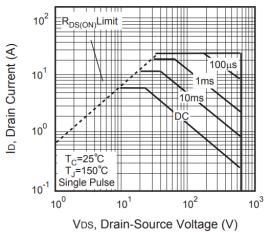
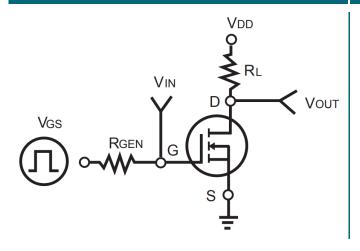


Fig. 9 • Switching Test Circuit

Fig. 10 • Switching Waveforms



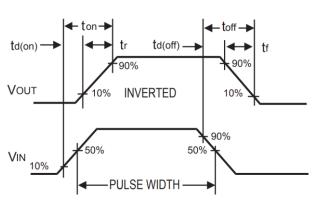
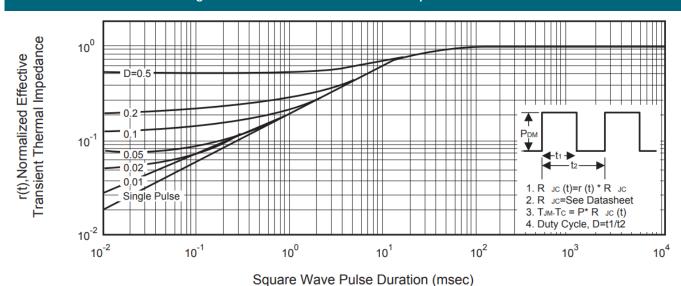


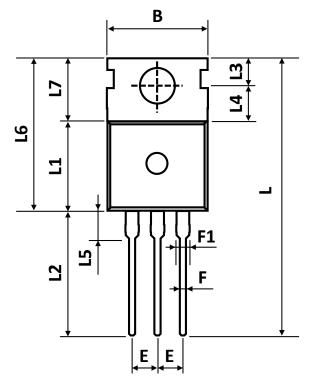
Fig. 11 - Normalized Thermal Transient Impedance Curve

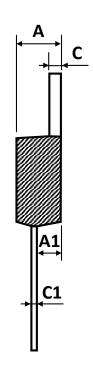


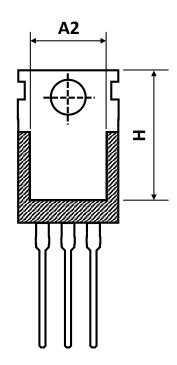
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## **PACKAGE OUTLINE**







Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
Α	4.43	4.53	4.63
A1	2.30	2.40	2.50
A2	7.70	7.90	8.10
В	9.80	10.00	10.20
С	1.25	1.30	1.40
C1	0.45	0.50	0.60
D	3.45	3.60	3.70
E	2.45	2.54	2.60
F	0.70	0.80	0.95
F1	1.15	1.33	1.50
L	26.80	28.80	30.80
L1	9.20	9.30	9.40
L2	12.80	13.10	13.40
L3	2.70	2.80	2.90
L4	3.50	3.70	3.80
L5	2.60	2.90	3.20
L6	15.40	15.80	16.20
L7	6.20	6.50	6.80
Н	12.95	13.25	13.55

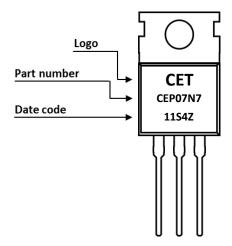
# **ORDERING INFORMATION**

Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
CEP07N7	TO-220-3L	Tube	50pcs	1,000pcs	4,000pcs

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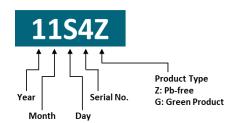


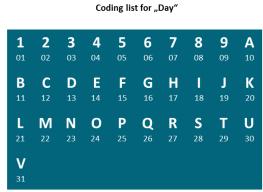
### **PART MARKING**



#### **DATE CODE**

Example: 11S4Z

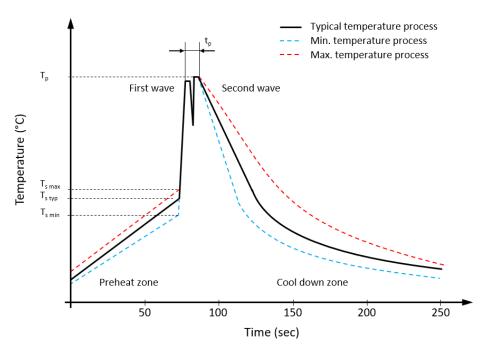








## RECOMMENDED WAVE SOLDERING PROFILE A THT PACKAGE



# Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	$T_{smin}$	100 °C	100 °C
Preheat temperature typical	T <sub>s typ</sub>	120 °C	120 °C
Preheat temperature max.	$T_{smax}$	130 °C	130 °C
Preheat time $t_s$ from $T_{smin}$ to $T_{smax}$	ts	70 seconds	70 seconds
Peak temperature	$T_p$	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t <sub>p</sub>	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes



#### **REVISION TABLE**

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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